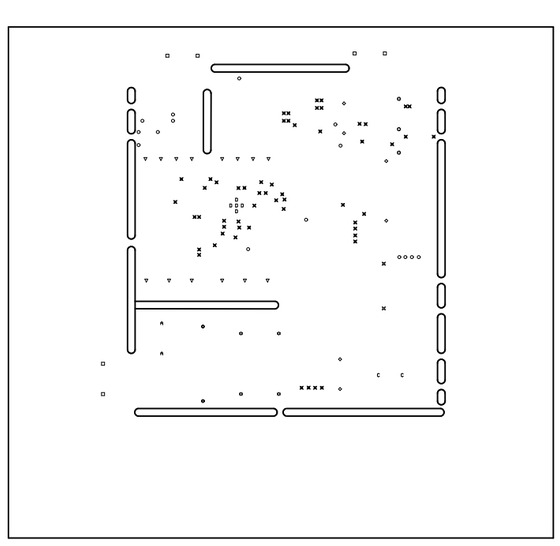
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 1	FR-4	8.00mil	4.2	
2	Signal Layer 1		1.40mil		
	Dielectric 2	FR-4	18.00mil	4.2	
3	Signal Layer 2		1.40mil		
	Dielectric 3	FR-4	8.00mil	4.2	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
D	5	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	15	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
✖	56	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
C	2	25.59mil (0.650mm)	PTH	Round	Top Layer - Bottom Layer	
▽	14	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	
◇	6	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
◎	2	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
⌑	2	37.40mil (0.950mm)	PTH	Round	Top Layer - Bottom Layer	
A	2	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
□	6	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
☼	4	53.15mil (1.350mm)	PTH	Round	Top Layer - Bottom Layer	
✪	3	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
	117 Total					

1000.00mil

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
☐ FR-408 ☒ FR-4 High Tg ☐ OTHER
THICKNESS: ☒ 40.4 MIL (1.0mm) +/-10% ☐ OTHER 40MIL
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER
SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER
☒ MATTE ☐ SEMI-GLOSS
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER
ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
☐ OUTER XX MIL VIAS REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: ZVS Aux Flyback
DESIGNED FOR: Public Release
FILE NAME: PMP23331.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23331	REV: A	SVN REV: Not in version control
LAYER NAME = [illegible]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 2/8/2023 4:52:31 PM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
Ben Lough	Ben Lough
SCALE: 1.00	ALTIUM DESIGNER VERSION: 21.2.2.38